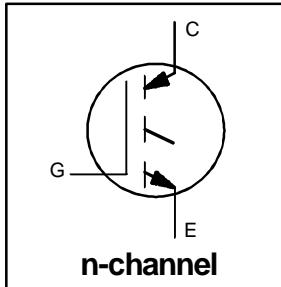


**INSULATED GATE BIPOLAR TRANSISTOR**

Short Circuit Rated  
Fast IGBT

**Features**

- Short circuit rated -  $10\mu\text{s}$  @  $125^\circ\text{C}$ ,  $V_{GE} = 15\text{V}$
- Switching-loss rating includes all "tail" losses
- Optimized for medium operating frequency (1 to 10kHz) See Fig. 1 for Current vs. Frequency curve

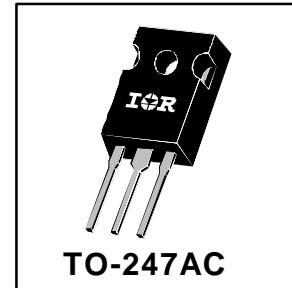


$V_{CES} = 600\text{V}$   
 $V_{CE(\text{sat})} \leq 2.3\text{V}$   
@  $V_{GE} = 15\text{V}$ ,  $I_C = 8.0\text{A}$

**Description**

Insulated Gate Bipolar Transistors (IGBTs) from International Rectifier have higher usable current densities than comparable bipolar transistors, while at the same time having simpler gate-drive requirements of the familiar power MOSFET. They provide substantial benefits to a host of high-voltage, high-current applications.

These new short circuit rated devices are especially suited for motor control and other applications requiring short circuit withstand capability.



**Absolute Maximum Ratings**

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ\text{C}$	Continuous Collector Current	13	A
$I_C @ T_C = 100^\circ\text{C}$	Continuous Collector Current	8.0	
$I_{CM}$	Pulsed Collector Current ①	26	
$I_{LM}$	Clamped Inductive Load Current ②	26	
$t_{sc}$	Short Circuit Withstand Time	10	$\mu\text{s}$
$V_{GE}$	Gate-to-Emitter Voltage	$\pm 20$	V
$E_{ARV}$	Reverse Voltage Avalanche Energy ③	5.0	mJ
$P_D @ T_C = 25^\circ\text{C}$	Maximum Power Dissipation	60	W
$P_D @ T_C = 100^\circ\text{C}$	Maximum Power Dissipation	24	
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting torque, 6-32 or M3 screw.	10 lbf•in (1.1N•m)	

**Thermal Resistance**

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	2.1	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	—	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	—	40	
Wt	Weight	—	6 (0.21)	—	g (oz)

**Electrical Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{CES}}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{\text{GE}} = 0\text{V}, I_C = 250\mu\text{A}$
$V_{(\text{BR})\text{ECS}}$	Emitter-to-Collector Breakdown Voltage <sup>④</sup>	20	—	—	V	$V_{\text{GE}} = 0\text{V}, I_C = 1.0\text{A}$
$\Delta V_{(\text{BR})\text{CES}/\Delta T_J}$	Temperature Coeff. of Breakdown Voltage	—	0.42	—	V/ $^\circ\text{C}$	$V_{\text{GE}} = 0\text{V}, I_C = 1.0\text{mA}$
$V_{\text{CE}(\text{on})}$	Collector-to-Emitter Saturation Voltage	—	2.0	2.3	V	$I_C = 8.0\text{A} \quad V_{\text{GE}} = 15\text{V}$
		—	2.7	—		$I_C = 13\text{A} \quad \text{See Fig. 2, 5}$
		—	2.5	—		$I_C = 8.0\text{A}, T_J = 150^\circ\text{C}$
		3.0	—	5.5		$V_{\text{CE}} = V_{\text{GE}}, I_C = 250\mu\text{A}$
$\Delta V_{\text{GE}(\text{th})/\Delta T_J}$	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/ $^\circ\text{C}$	$V_{\text{CE}} = V_{\text{GE}}, I_C = 250\mu\text{A}$
$g_{\text{fe}}$	Forward Transconductance <sup>⑤</sup>	2.7	3.8	—	S	$V_{\text{CE}} = 100\text{V}, I_C = 8.0\text{A}$
$I_{\text{CES}}$	Zero Gate Voltage Collector Current	—	—	250	$\mu\text{A}$	$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}$
		—	—	1000		$V_{\text{GE}} = 0\text{V}, V_{\text{CE}} = 600\text{V}, T_J = 150^\circ\text{C}$
$I_{\text{GES}}$	Gate-to-Emitter Leakage Current	—	—	$\pm 100$	nA	$V_{\text{GE}} = \pm 20\text{V}$

**Switching Characteristics @  $T_J = 25^\circ\text{C}$  (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions
$Q_g$	Total Gate Charge (turn-on)	—	16	24	nC	$I_C = 8.0\text{A}$
$Q_{\text{ge}}$	Gate - Emitter Charge (turn-on)	—	3.6	5.2		$V_{\text{CC}} = 400\text{V} \quad \text{See Fig. 8}$
$Q_{\text{gc}}$	Gate - Collector Charge (turn-on)	—	6.0	9.0		$V_{\text{GE}} = 15\text{V}$
$t_{d(\text{on})}$	Turn-On Delay Time	—	29	—	ns	$T_J = 25^\circ\text{C}$
$t_r$	Rise Time	—	22	—		$I_C = 8.0\text{A}, V_{\text{CC}} = 480\text{V}$
$t_{d(\text{off})}$	Turn-Off Delay Time	—	270	400		$V_{\text{GE}} = 15\text{V}, R_G = 50\Omega$
$t_f$	Fall Time	—	280	510		Energy losses include "tail"
$E_{\text{on}}$	Turn-On Switching Loss	—	0.14	—	mJ	See Fig. 9, 10, 11, 14
$E_{\text{off}}$	Turn-Off Switching Loss	—	0.86	—		
$E_{\text{ts}}$	Total Switching Loss	—	1.0	2.0		
$t_{\text{sc}}$	Short Circuit Withstand Time	10	—	—	$\mu\text{s}$	$V_{\text{CC}} = 360\text{V}, T_J = 125^\circ\text{C}$ $V_{\text{GE}} = 15\text{V}, R_G = 50\Omega, V_{\text{CPK}} < 500\text{V}$
$t_{d(\text{on})}$	Turn-On Delay Time	—	27	—	ns	$T_J = 150^\circ\text{C},$ $I_C = 8.0\text{A}, V_{\text{CC}} = 480\text{V}$
$t_r$	Rise Time	—	21	—		$V_{\text{GE}} = 15\text{V}, R_G = 50\Omega$
$t_{d(\text{off})}$	Turn-Off Delay Time	—	370	—		Energy losses include "tail"
$t_f$	Fall Time	—	420	—		See Fig. 10, 14
$E_{\text{ts}}$	Total Switching Loss	—	1.4	—	mJ	See Fig. 10, 14
$L_E$	Internal Emitter Inductance	—	13	—	nH	Measured 5mm from package
$C_{\text{ies}}$	Input Capacitance	—	365	—	pF	$V_{\text{GE}} = 0\text{V}$
$C_{\text{oes}}$	Output Capacitance	—	47	—		$V_{\text{CC}} = 30\text{V} \quad \text{See Fig. 7}$
$C_{\text{res}}$	Reverse Transfer Capacitance	—	4.8	—		$f = 1.0\text{MHz}$

**Notes:**

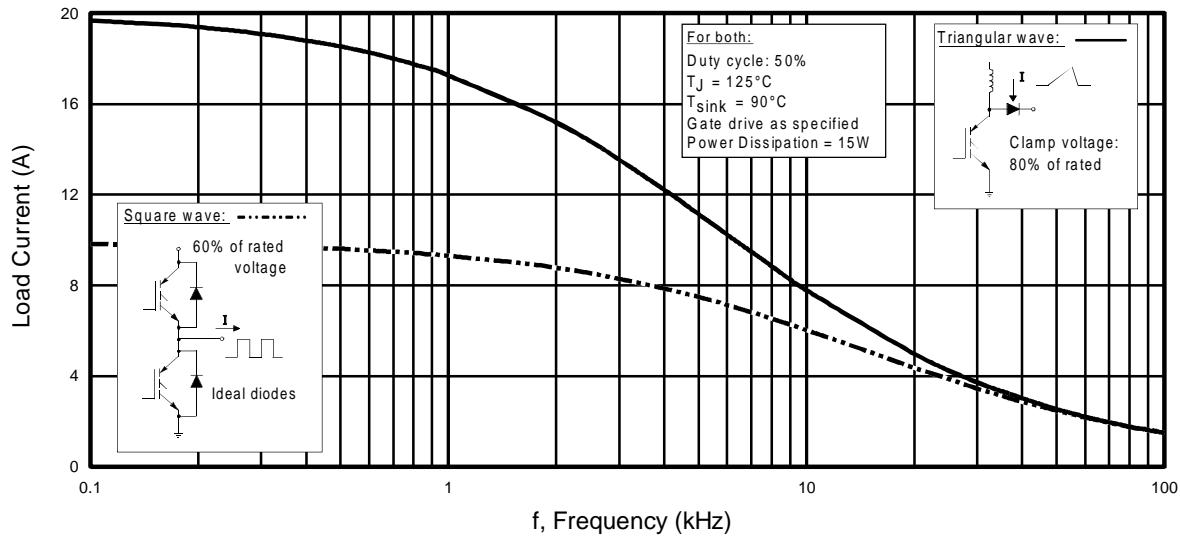
① Repetitive rating;  $V_{\text{GE}}=20\text{V}$ , pulse width limited by max. junction temperature.  
( See fig. 13b )

②  $V_{\text{CC}}=80\%(V_{\text{CES}})$ ,  $V_{\text{GE}}=20\text{V}$ ,  $L=10\mu\text{H}$ ,  $R_G=50\Omega$ , ( See fig. 13a )

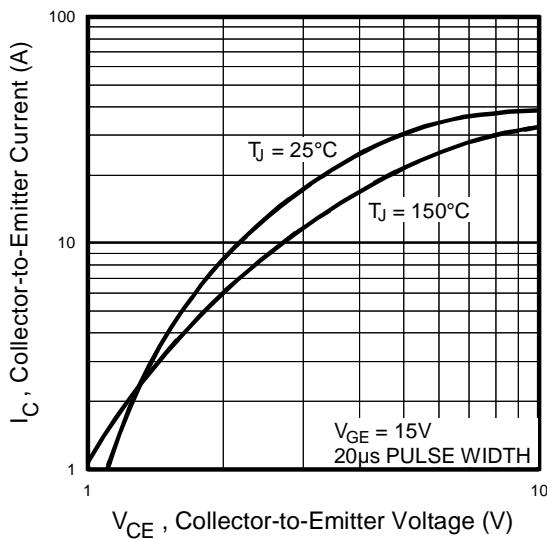
③ Repetitive rating; pulse width limited by maximum junction temperature.

④ Pulse width  $\leq 80\mu\text{s}$ ; duty factor  $\leq 0.1\%$ .

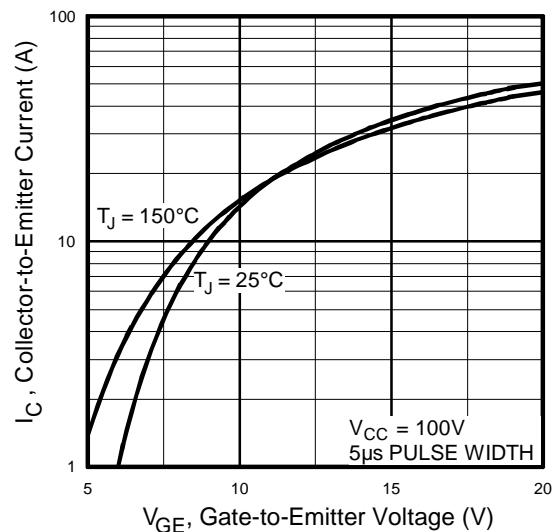
⑤ Pulse width  $5.0\mu\text{s}$ , single shot.



**Fig. 1 - Typical Load Current vs. Frequency**  
(For square wave,  $I=I_{\text{RMS}}$  of fundamental; for triangular wave,  $I=I_{\text{PK}}$ )

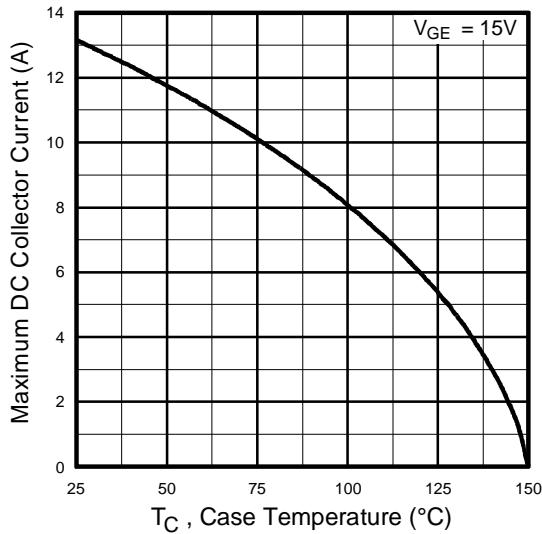


**Fig. 2 - Typical Output Characteristics**

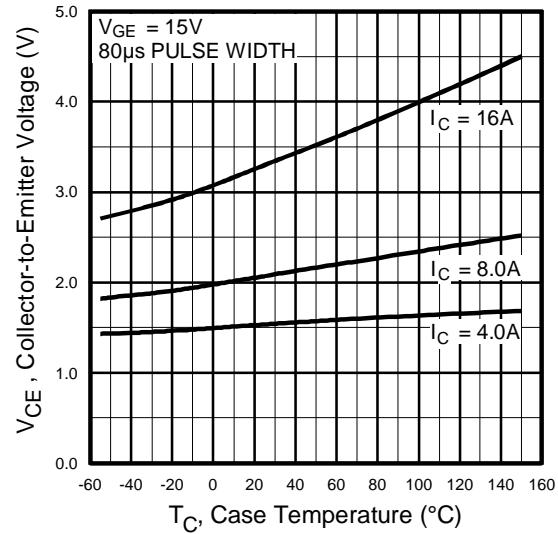


**Fig. 3 - Typical Transfer Characteristics**

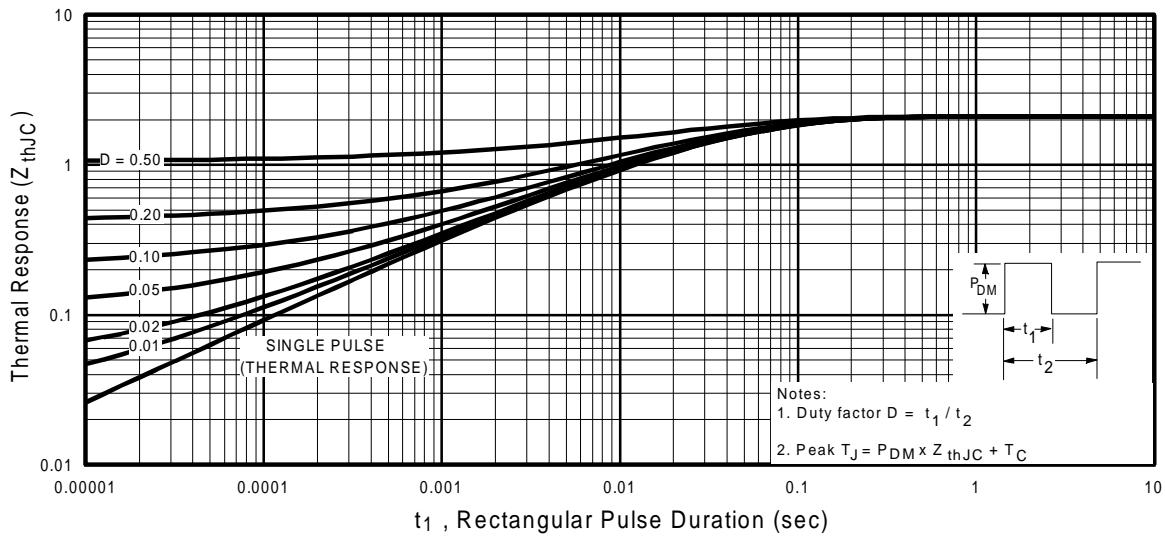
# IRGPC20M



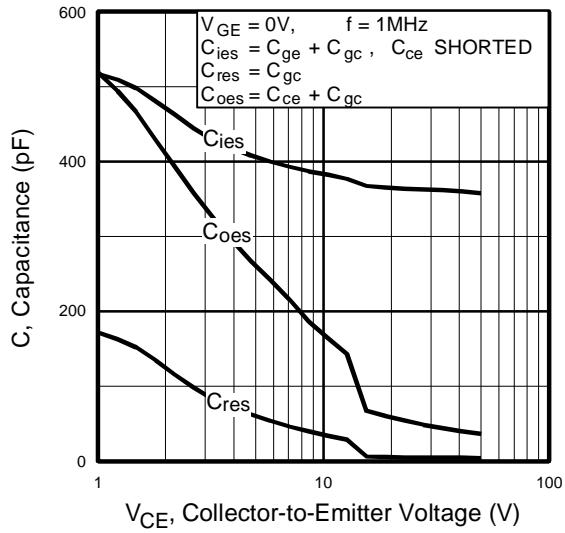
**Fig. 4 - Maximum Collector Current vs. Case Temperature**



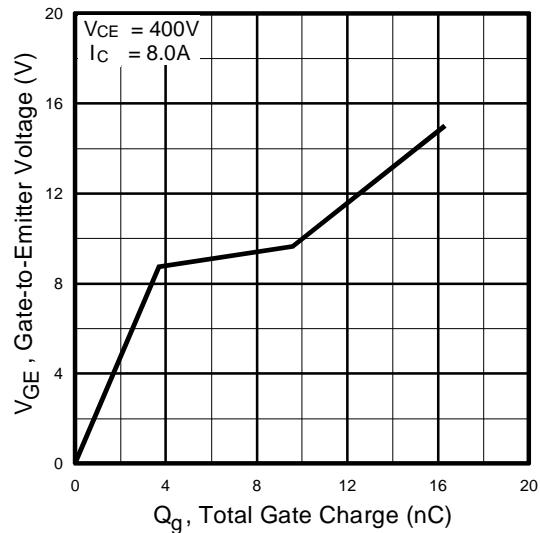
**Fig. 5 - Collector-to-Emitter Voltage vs. Case Temperature**



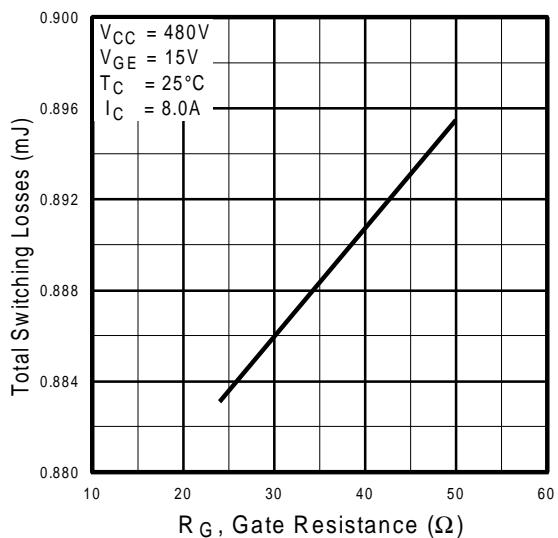
**Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



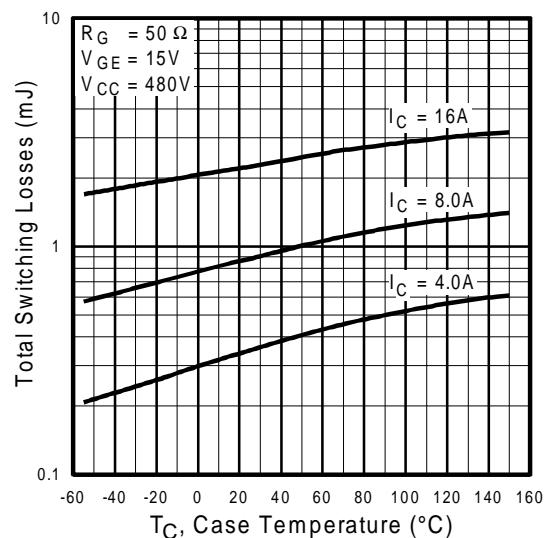
**Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage**



**Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage**

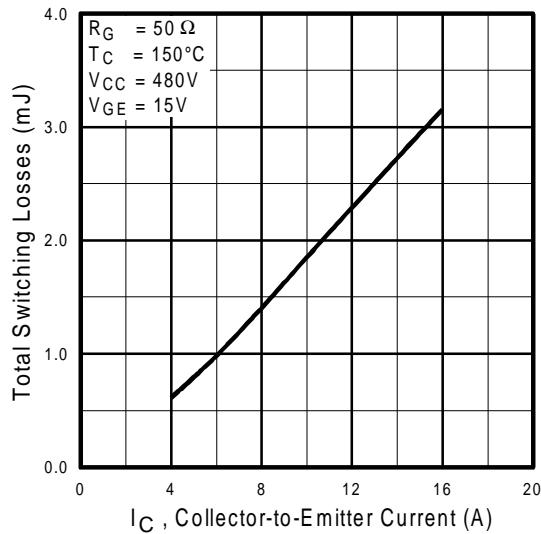


**Fig. 9 - Typical Switching Losses vs. Gate Resistance**

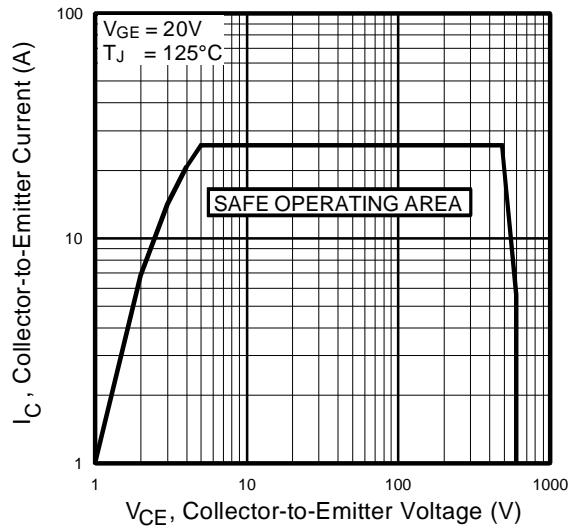


**Fig. 10 - Typical Switching Losses vs. Case Temperature**

# IRGPC20M



**Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current**



**Fig. 12 - Turn-Off SOA**

**Refer to Section D for the following:**

## Appendix C: Section D - page D-5

- Fig. 13a - Clamped Inductive Load Test Circuit
- Fig. 13b - Pulsed Collector Current Test Circuit
- Fig. 14a - Switching Loss Test Circuit
- Fig. 14b - Switching Loss Waveform

**Package Outline 3 - JEDEC Outline TO-247AC**

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